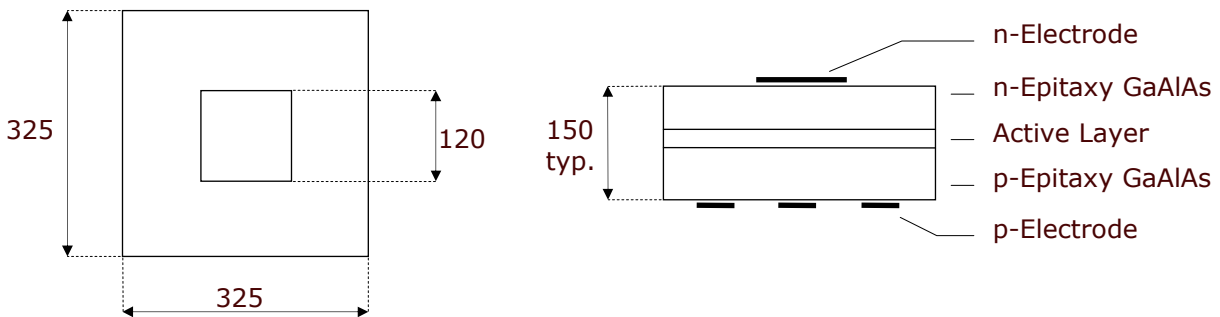


**INFRA-RED**

**Item No.: 115161 H**

1. This specification applies to GaAlAs / GaAlAs Chips (substrate removed)
2. Structure
  - 2.1 Mesa structure
  - 2.2 Electrodes
 

|                  |          |
|------------------|----------|
| p-side (anode)   | Au alloy |
| n-side (cathode) | Au alloy |
3. Outlines (dimensions in microns)



Wire bond contacts can also have a spider shape

4. Electrical and optical characteristics (T=25°C)

| Parameter       | Symbol      | Conditions                     | min | typ  | max  | Unit |
|-----------------|-------------|--------------------------------|-----|------|------|------|
| Forward voltage | $V_F$       | $I_F = 20 \text{ mA}$          |     | 1,90 | 2,30 | V    |
| Reverse voltage | $V_R$       | $I_R = 10 \text{ }\mu\text{A}$ | 5   |      |      | V    |
| output Power *  | $\Phi_e$    | $I_F = 20 \text{ mA}$          | 1,3 | 1,65 |      | mW   |
| Switching time  | $t_r, t_f$  | $I_F = 20 \text{ mA}$          |     | 40   |      | ns   |
| Peak wavelength | $\lambda_p$ | $I_F = 20 \text{ mA}$          |     | 680  |      | nm   |

Power measurement at OSA on gold plate

5. Packing
  - 1) wire bond side on top
  - 2) back contact on top

6. Labeling

| Type | Lot No. | $\Phi_e$ typ<br>min<br>max | Quantity |
|------|---------|----------------------------|----------|
|------|---------|----------------------------|----------|